

PATENT ASSIGNMENT COVER SHEET

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 Stylesheet Version v1.2

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SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
	SIXPOINT MATERIALS, INC.	11/29/2017
RECEIVING PARTY DATA		
Name:	SEOUL SEMICONDUCTOR CO., LTD.	
Street Address:	97-11, SANDAN-RO 163BEON-GIL, DANWON-GU	
City:	ANSAN-SI, GYEONGGI-DO	
State/Country:	KOREA, REPUBLIC OF	
Postal Code:	15429	
PROPERTY NUMBERS Total: 1		
	Property Type	Number
	Patent Number:	9754782
CORRESPONDENCE DATA		
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<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>		
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Correspondent Name:	STRATEGIC INNOVATION IP LAW OFFICES, P.C.	
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ATTORNEY DOCKET NUMBER:	SIXPOI-023US1	
NAME OF SUBMITTER:	CHARLES D. HOLLAND	
SIGNATURE:	/ Charles D. Holland /	
DATE SIGNED:	12/28/2017	
Total Attachments: 2		
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ASSIGNMENT

This Assignment by SixPoint Materials, Inc., a corporation organized and existing under the laws of Delaware and having a usual place of business at 37 Industrial Way, Unit 106, Buellton, CA 93427 (hereinafter referred to as the assignor), witnesseth:

WHEREAS, said assignor owns the entire right, title, and interest in the invention(s) described in U.S. patent application number 14/959,476 entitled "GROUP III NITRIDE SUBSTRATES AND THEIR FABRICATION METHOD" filed on December 4, 2015, issued as U.S. Patent No. 9,754,782;

WHEREAS, Seoul Semiconductor Co., Ltd. (hereinafter "ASSIGNEE"), a corporation organized and existing under the laws of the Republic of Korea, and having a usual place of business at 97-11, Sandan-ro 163beon-gil, Danwon-gu, Ansan-si, Gyeonggi-do, 15429, Republic of Korea, desires to acquire an interest therein, in accordance with agreements duly entered into with us/me;

NOW, THEREFORE, to all whom it may concern, be it known that, for and in consideration of said agreements and of other good and valuable consideration, the receipt of which is hereby acknowledged, we/I have sold, assigned and transferred and by these presents do hereby sell, assign and transfer unto said ASSIGNEE, a fifty percent (50%) undivided interest, in and throughout the United States of America, its territories and all foreign countries, in and to the invention(s) described in said applications, together with a fifty percent (50%) undivided interest in and to said applications and such Patents as may issue thereon or claim priority under United States law or international convention, including but not limited to non-provisionals, continuations, continuations-in-part, divisionals, reissues, reexaminations, extensions, and substitutions of said application or such Patents, said invention(s), applications and Patents to be held and enjoyed by said ASSIGNEE for its own use and behalf and for such of ASSIGNEE's Affiliates as are permitted under the "IP Agreement" dated November 23, 2012, to the full end of the term for which said Patents may be granted, provided that if ASSIGNEE before November 23, 2017 fails to pay any costs for a filing related to the invention(s) described in any of said applications, ASSIGNEE by its signature below hereby assigns all of its rights, title, and interest in and to the invention(s) and said applications for which said costs were not paid to assignor or assignor's successors in interest;

AND, we/I hereby further agree for ourselves/myself and our/my executors and administrators to execute upon request any other lawful documents and likewise to perform any other lawful acts which may be deemed necessary to secure fully the interest in the aforesaid invention(s) to said ASSIGNEE, but at its or their expense and charges, including the execution of non-provisional, substitution, continuation, continuation-in-part, divisional, reissue, reexamination, or corresponding foreign or international patent applications;

ASSIGNMENT SIXPOINT MATERIALS, INC. TO
SEOUL SEMICONDUCTOR CO., LTD.

AND, we/I hereby further agree to provide statements or testimony in any interference or other proceeding in which said invention(s) or any application or patent directed thereto may be involved;

AND, subject to the terms herein, we/I hereby authorize and request the Director of the United States Patent and Trademark Office and the empowered officials of all other governments to issue such Patent as shall be granted upon said applications, or applications based thereon, to include said ASSIGNEE as a joint owner.

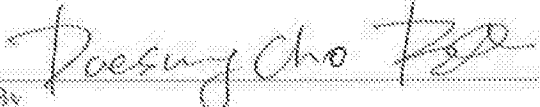
IN TESTIMONY WHEREOF, we/I have hereunto set our/my signatures on the date(s) set forth below.

11/29/2017
Date


By Tadeo Hashimoto, CEO
SixPoint Materials, Inc.
37 Industrial Way, Unit 106
Buellton, CA 93427
U.S.A.

Assignee hereby accepts the assignment of an interest in the invention(s) and the above-identified applications and/or patents. Assignee also acknowledges by signature below that no attorney-client relationship is established between Assignee and Assignor's attorneys by virtue of this ownership or ownership of other patent applications or by powers of attorney provided by Assignor for co-owned patent applications, and Assignor's attorneys shall continue to seek instruction from and advise Assignor exclusively for Assignor's benefit.

Dec. 1. 2017
Date


By
Seoul Semiconductor Co., Ltd.